

L Number	Hits	Search Text	DB	Time stamp
1	11	((test or testing or tested) with electrical with (poor and good)) not (@ad>19990114 or @rlad>19990114)	USPAT;	2003/02/21
17	593	"PEELING LAYER"	US-PGPUB	10:30
18	8906	flip-chip or "flip chip"	USPAT;	2003/02/21
19	519609	bond or bonding or bonded	US-PGPUB	12:21
20	642783	@ad>19990114 or @rlad>19990114	USPAT;	2003/02/21 14:51
21	6	"PEELING LAYER" AND (flip-chip or "flip chip") AND (bond or bonding or bonded)	US-PGPUB	2003/02/21 14:51
22	1	("PEELING LAYER" AND (flip-chip or "flip chip") AND (bond or bonding or bonded)) NOT (@ad>19990114 or @rlad>19990114)	USPAT;	2003/02/21
23	7	"PEELING LAYER" AND (flip-chip or "flip chip")	US-PGPUB	12:22
24	2	("PEELING LAYER" AND (flip-chip or "flip chip")) NOT (@ad>19990114 or @rlad>19990114)	USPAT;	2003/02/21
25	39589	(test or testing or tested) and (peeling or peel or peeled)	US-PGPUB	12:22
26	330	(flip-chip or "flip chip") and ((test or testing or tested) and (peeling or peel or peeled))	USPAT;	2003/02/21
27	151	((flip-chip or "flip chip") and ((test or testing or tested) and (peeling or peel or peeled))) not (@ad>19990114 or @rlad>19990114)	US-PGPUB	12:25
28	2281	adhesive with "thermoplastic resin"	USPAT;	2003/02/21
29	1749	(adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114)	US-PGPUB	12:25
30	34	(flip-chip or "flip chip") and ((adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114))	USPAT;	2003/02/21
31	1649	adhesive with "thermosetting resin"	US-PGPUB	12:28
32	245	((adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114)) and (adhesive with "thermosetting resin")	USPAT;	2003/02/21 14:51
33	12	(flip-chip or "flip chip") and (((adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114)) and (adhesive with "thermosetting resin"))	US-PGPUB	2003/02/21
34	51	adhesive with "low melting point metal"	USPAT;	12:29
35	34	(adhesive with "low melting point metal") not (@ad>19990114 or @rlad>19990114)	US-PGPUB	2003/02/21
36	8	(flip-chip or "flip chip") and ((adhesive with "low melting point metal") not (@ad>19990114 or @rlad>19990114))	USPAT;	13:32
37	15	"torsional force" with adhesive	US-PGPUB	2003/02/21
38	774960	test or testing or tested	USPAT;	13:27
39	8	("torsional force" with adhesive) and (test or testing or tested)	US-PGPUB	2003/02/21
40	6	((("torsional force" with adhesive) and (test or testing or tested)) not (@ad>19990114 or @rlad>19990114))	USPAT;	2003/02/21
41	12	("torsional force" with adhesive) not (@ad>19990114 or @rlad>19990114)	US-PGPUB	13:36
42	6	((("torsional force" with adhesive) not (@ad>19990114 or @rlad>19990114)) not (((("torsional force" with adhesive) and (test or testing or tested)) not (@ad>19990114 or @rlad>19990114)))	USPAT;	2003/02/21
43	197	torsional with adhesive	US-PGPUB	13:40
44	167	(torsional with adhesive) not (@ad>19990114 or @rlad>19990114)	USPAT;	2003/02/21
45	391738	semiconductor or "integrated circuit"	US-PGPUB	13:42

46	8	((torsional with adhesive) not (@ad>19990114 or @rlad>19990114)) and (semiconductor or "integrated circuit")	USPAT; US-PGPUB	2003/02/21 13:49
47	54	fluororesin with peeling	USPAT; US-PGPUB	2003/02/21 13:49
48	32	(fluororesin with peeling) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 13:50
49	0	(flip-chip or "flip chip") and ((fluororesin with peeling) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/21 13:50
50	19	(bond or bonding or bonded) and ((fluororesin with peeling) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/21 14:25
51	180	fluororesin with (bond or bonding or bonded)	USPAT; US-PGPUB	2003/02/21 14:26
52	111	(fluororesin with (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 14:26
53	0	(flip-chip or "flip chip") and ((fluororesin with (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/21 14:26
54	28	(semiconductor or "integrated circuit") and ((fluororesin with (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/21 14:26
55	6369	flip-chip or "flip chip"	EPO; JPO; DERWENT	2003/02/21 14:51
56	543223	bond or bonding or bonded	EPO; JPO; DERWENT	2003/02/21 14:51
57	400960	(test or testing or tested)	EPO; JPO; DERWENT	2003/02/21 14:52
58	10784	(test or testing or tested) with electrical	EPO; JPO; DERWENT	2003/02/21 14:52
59	10	(flip-chip or "flip chip") and (bond or bonding or bonded) and ((test or testing or tested) with electrical)	EPO; JPO; DERWENT	2003/02/21 14:52
-	91785	peel\$	USPAT; US-PGPUB	2003/02/20 12:10
-	521	438/15.ccls.	USPAT; US-PGPUB	2003/02/20 12:10
-	596	peel\$ and (flip-chip or "flip chip") and (bond or bonding or bonded)	USPAT; US-PGPUB	2003/02/20 12:10
-	248	(peel\$ and (flip-chip or "flip chip") and (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/20 12:10
-	6	438/15.ccls. and ((peel\$ and (flip-chip or "flip chip") and (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/20 12:22
-	612	438/17.ccls.	USPAT; US-PGPUB	2003/02/20 12:23
-	2	((peel\$ and (flip-chip or "flip chip") and (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114)) and 438/17.ccls.	USPAT; US-PGPUB	2003/02/20 12:23
-	673	438/108.ccls.	USPAT; US-PGPUB	2003/02/20 12:23
-	5	((peel\$ and (flip-chip or "flip chip") and (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114)) and 438/108.ccls.	USPAT; US-PGPUB	2003/02/20 12:30
-	242	438/119.ccls.	USPAT; US-PGPUB	2003/02/20 12:30
-	3	((peel\$ and (flip-chip or "flip chip") and (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114)) and 438/119.ccls.	USPAT; US-PGPUB	2003/02/20 12:34
-	709	438/613.ccls.	USPAT; US-PGPUB	2003/02/20 12:34
-	11	((peel\$ and (flip-chip or "flip chip") and (bond or bonding or bonded)) not (@ad>19990114 or @rlad>19990114)) and 438/613.ccls.	USPAT; US-PGPUB	2003/02/20 12:36
-	48	(flip-chip or "flip chip") and 438/17.ccls.	USPAT; US-PGPUB	2003/02/20 12:40
-	28814	test\$ with electrical	USPAT; US-PGPUB	2003/02/20 12:42

-	28146	(test or testing or tested) with electrical	USPAT; US-PGPUB	2003/02/20 13:01
-	204	438/17.ccls. and ((test or testing or tested) with electrical)	USPAT; US-PGPUB	2003/02/20 12:43
-	126	(438/17.ccls. and ((test or testing or tested) with electrical)) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/20 12:43
-	16	(flip-chip or "flip chip") and ((438/17.ccls. and ((test or testing or tested) with electrical)) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/20 13:00
-	17	(test or testing or tested) with electrical with (poor and good)	USPAT; US-PGPUB	2003/02/20 13:02